

P R E S S R E L A S E

X-FAB Offers Multi-Project Wafer Runs through EUROPRACTICE IC Service

***Unique combination of high-voltage and Flash memory technology now available
to European academia and start-ups for IC prototyping***

ERFURT, Germany – Jan. 28, 2014 – Analog/mixed-signal foundry group [X-FAB Silicon Foundries](#) today announced its collaboration with Belgian-based micro- and nanoelectronics research center [imec](#) to offer multi-project wafer runs through imec's [EUROPRACTICE IC Service](#) for X-FAB's 0.18 micrometer SOI HV process (XT018) and a junction-isolated HV process (XH018). The offered service enables small start-ups and academic institutions throughout Europe to access the full functionality of X-FAB's unique high-voltage/low-power 0.18 micrometer technology and prototype ASIC designs in a very cost-effective way.

Imec is one of the world's leading independent R&D institutes for nano-electronics and semiconductors. The EUROPRACTICE IC Service offered by imec and Fraunhofer brings ASIC design and manufacturing capability within the technical and financial reach of anyone who wishes to use ASICs. It offers low-cost ASIC prototyping and small volume production ramp-up to European universities and publicly funded research institutes for microelectronic and microsystem design through multi-project wafer (MPW) and dedicated wafer runs. To see the X-FAB listings on the MPW schedule for 2014, please click [here](#).

X-FAB CEO Rudi De Winter said, "Through our cooperation with imec's EUROPRACTICE Service we access an innovative network of start-up companies, universities and institutes across Europe. One growth area in which Europe is playing a leading role is the More than Moore domain. Offering technologies to integrate more and more functions in one IC, such as analog components, high-voltage electronics, non-volatile memories and controllers is X-FAB's core competency. We believe that our collaboration with imec offers new opportunities for semiconductor researchers and developers in Europe to continue to innovate in the field of More than Moore."

X-FAB's [XH018](#) is the first and only 0.18 micrometer platform with high-temperature, high-voltage (HV) and non-volatile memory (NVM) capability including Flash and NVRAM IP. This modular mixed-signal high-voltage CMOS technology extends the operating temperature range of integrated circuits to +175°C. With the ability to integrate HV and NVM in a single platform, it is ideal for automotive applications and for motor control and power management or power-conversion applications for a wide range of voltages in industrial, medical and consumer systems.

X-FAB's [XT018](#) is the only trench dielectric isolated SOI foundry process with 200V MOS capability at 180nm. With an operating temperature range of -40 to 175°C, it supports a new generation of cost-effective "Super Smart Power" technologies. The XT018 process is ideally suited for high-performance systems requiring multiple voltage domains integrated and isolated in one chip. For example, it is useful for medical ultrasound applications and for applications that need bidirectional isolation, such as piezo actuators and capacitive-driven micromechanics.

Availability

MPW service for X-FAB's XT018 and XH018 technology is available now through EURORACTICE at: http://www.europractice-ic.com/technologies_XFAB.php.

About X-FAB

X-FAB is the leading analog/mixed-signal foundry group manufacturing silicon wafers for analog-digital integrated circuits (mixed-signal ICs). X-FAB maintains wafer production facilities in Erfurt, Dresden and Itzehoe (Germany), Lubbock, Texas (US) and Kuching, Sarawak (Malaysia), and employs approximately 2,400 people worldwide. It manufactures wafers based on advanced modular CMOS and BiCMOS processes with technologies ranging from 1.0 to 0.13 micrometers, for applications primarily in the automotive, communications, consumer and industrial sectors. For more information, please visit www.xfab.com.

Acronyms

ASIC	Application-Specific Integrated Circuit
BiCMOS	Bi-polar Complementary Metal-Oxide-Semiconductor
CMOS	Complementary Metal-Oxide-Semiconductor
HV	High Voltage
IC	Integrated Circuit
IP	Intellectual Property
MPW	Multi-Project Wafer
NVM	Non-Volatile Memory
R&D	Research and Development
SOI	Silicon on Insulator

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